CLAIMS

1. A method for inspecting a semiconductor package, the method including:

casting a shadow of a bonded wire onto the semiconductor package;

obtaining a 3D image of the semiconductor package;

determining a distance S of the shadow and the bonded wire in the image; and

obtaining a wire loop height H of the bonded wire.

2. The method of claim 1, wherein a plurality of the distance S is determined to compute a height profile of a length of the bonded wire.

3. The method of claim 1, wherein the 3D image is obtained using a 3D camera with an imaging lens positioned at a first angle ß relative to a normal axis of the semiconductor package.

4. The method of claim 3, wherein the shadow is cast using a light source positioned at a second angle α relative to the normal axis, opposite to the 3D camera.

5. The method of claim 4, wherein the wire loop height H is $S \cdot \cos(\alpha)/\sin(\alpha+ß)$.